

# COG FINAL BOND MACHINE TM-808P



## OVERVIEW

**TM-808P** provides the final thermo-compression of pre-bonded COG modules. Integrated with *Cherusal*<sup>TM</sup> Pulse Heat system, the **Intelli-Pulse** controller ensures precise and accurate temperature profile at any stage of the bonding process. Bonding pressure is controlled electronically for consistent output bonding force. All other considerations for bonding such as co-planarity adjustment and built vacuum are available in the machine to achieve good and reliable final bond quality.

## FEATURES & BENEFITS

- Semi Automatic Operation
- Integrated with *Cherusal*<sup>TM</sup> Pulse Heat system
- **Intelli-Pulse** controller
- Suitable for a wide range of substrate sizes
- Co-planarity Adjustment Mechanism
- Touch Panel User Interface with Real Time Temperature Profile
- Manual Mode Function for machine set up
- User Pre-set Password

# COG FINAL BOND MACHINE TM-808P

## SPECIFICATIONS

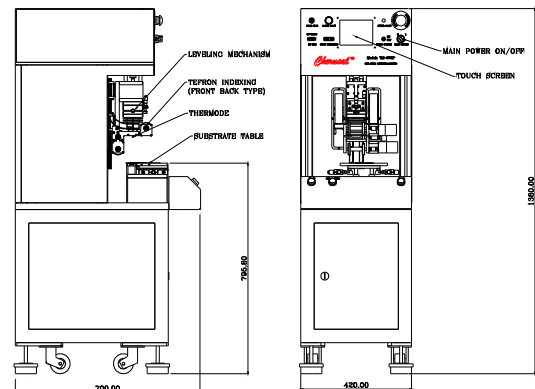
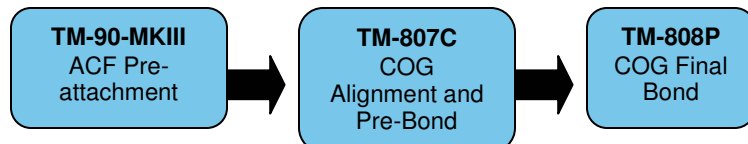
<b>Machine Specs</b>		
Power Supply	Single Phase, 230 V $\pm$ 10%, 50Hz/ 60Hz, 3.5KVA	
Operating Ambient	23 $\pm$ 5 $^{\circ}$ C, 40% ~ 100% Humidity, Controlled Environment	
Air Pressure Supply	Filtered Clean and Dry Air, 6 Kg/cm <sup>2</sup>	
Control System	Microprocessor Based	
Vacuum Source	Vacuum Ejector -84kPa	
Silicone or Teflon Rubber Indexing	Yes	
Co-planarity Adjustment	Yes	
User Interface	Touch Panel User Interface	
Real Time Temp. Display	Yes	
Pressure Control	Electronics Pressure Regulator	
Password	User Pre-set	
Machine Dimension	420mm (L) x 700mm (W) x 1380mm (H)	
Machine Weight	Approx. 250 kg	
<b>Final Bond Specs</b>		
Final Bond	Heating Method	Pulse Heated
	Ramp Temp.	RT ~ 450 $^{\circ}$ C (max)
	Ramp Period	1 sec ~ 25 sec
	Hold Period	1 sec ~ 100 sec
	Release Temp.	RT ~ 450 $^{\circ}$ C
Temp. ramp stages	04	
Bonding Force	1.5Kgf ~ 44Kgf	
Bonding Accuracy	$\leq$ 3 $\mu$ m	
<b>Thermode Specs</b>		
Thermode Flatness	$\pm$ 3 $\mu$ m ( at room temperature)	
Thermode Material	Hotvar	
Thermocouple Type	K Type	
Max. Thermode Dimensions	38mm x 6mm	
<b>IC/Substrates Specs</b>		
IC Dimensions	1.0mm x 3mm ~ 5mm x 25mm	
Substrate Dimensions	20mm x 20mm ~ 130mm x 200mm	
Loading Method	Front with side guide	

Specifications are subjected to change without prior notice

### OPTIONS

- Area sensors
- Ionisers
- Vision System

### OPTIONS FOR OTHER PRODUCTION METHODS



### HEADQUARTER (SINGAPORE)



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